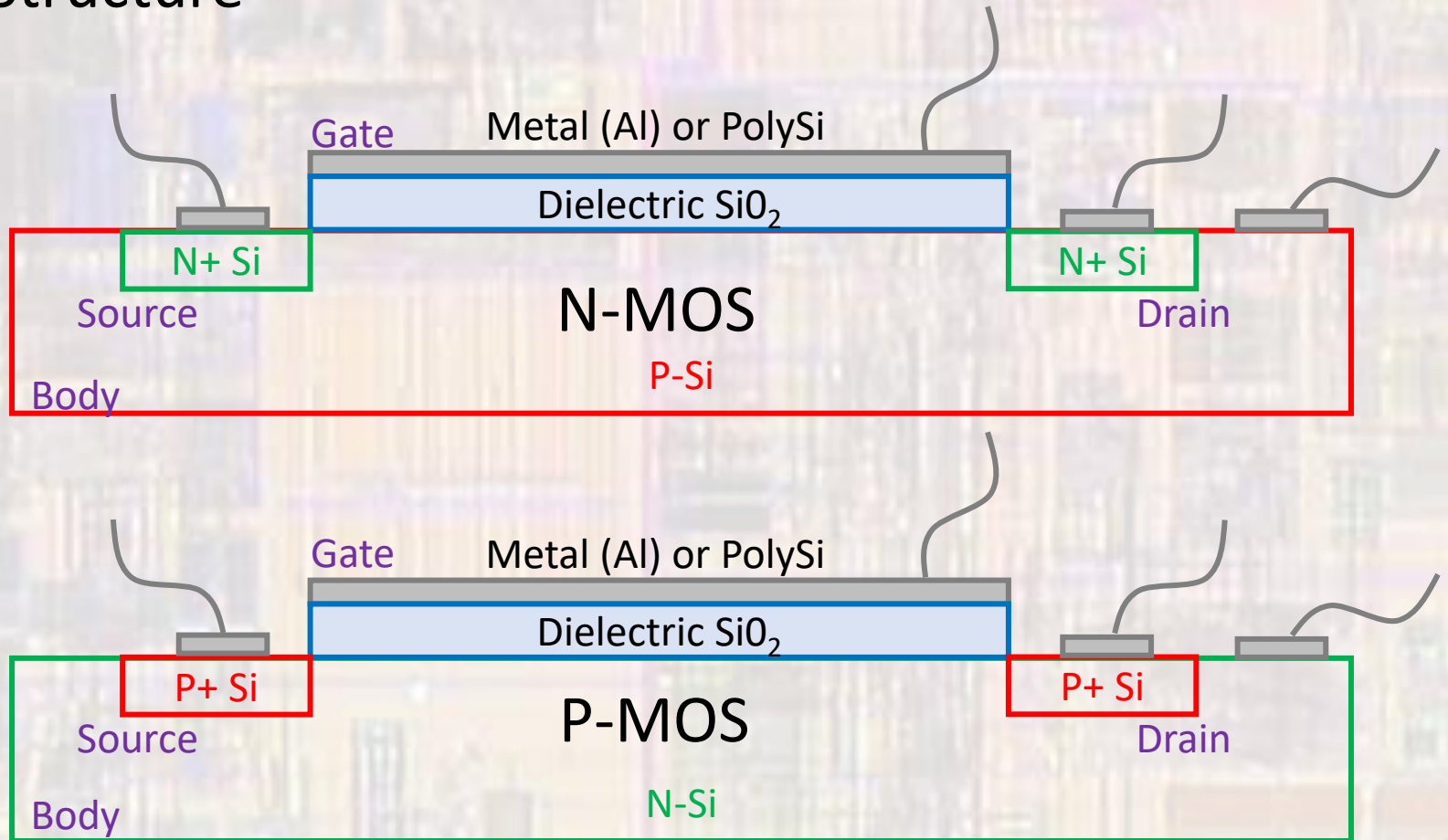


MOS Transistors

Last updated 1/11/24

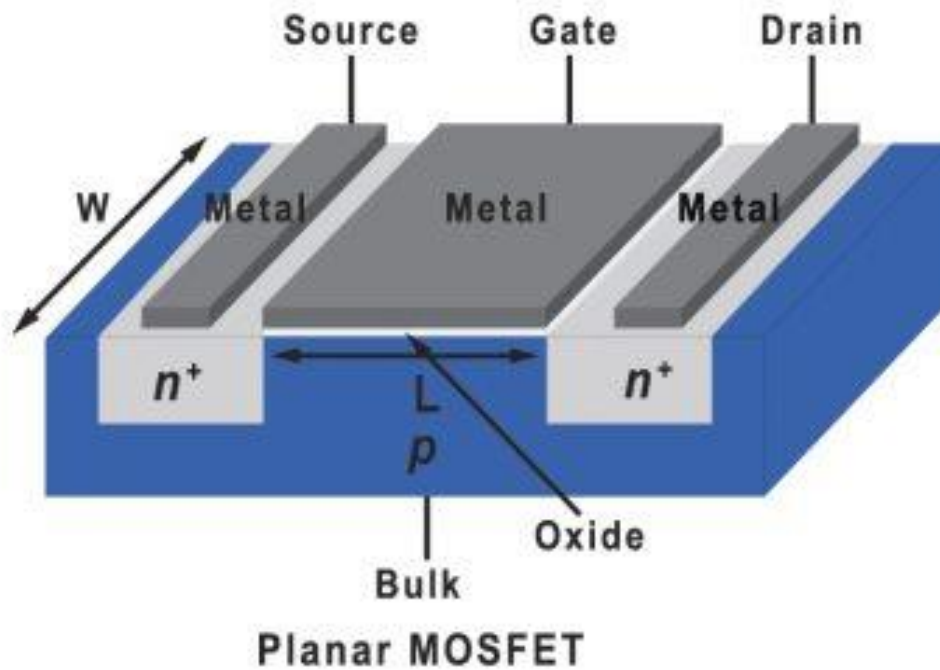
MOS Enhancement Mode Transistor

- Structure



MOS Enhancement Mode Transistor

- Structure



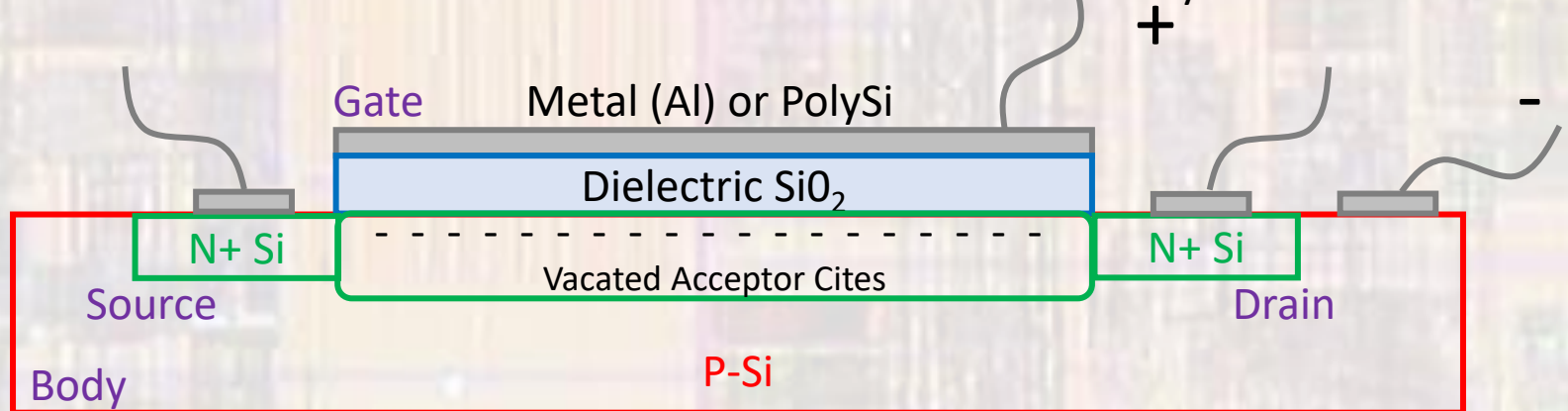
MOS Enhancement Mode Transistor

- N-MOS Operation

- **Large** Positive Bias

- Depletion region is formed

- Mobile holes pushed away (region is depleted of holes)
- Net negative (fixed) charge left behind
- Electrons are drawn from the Si to form an inversion layer

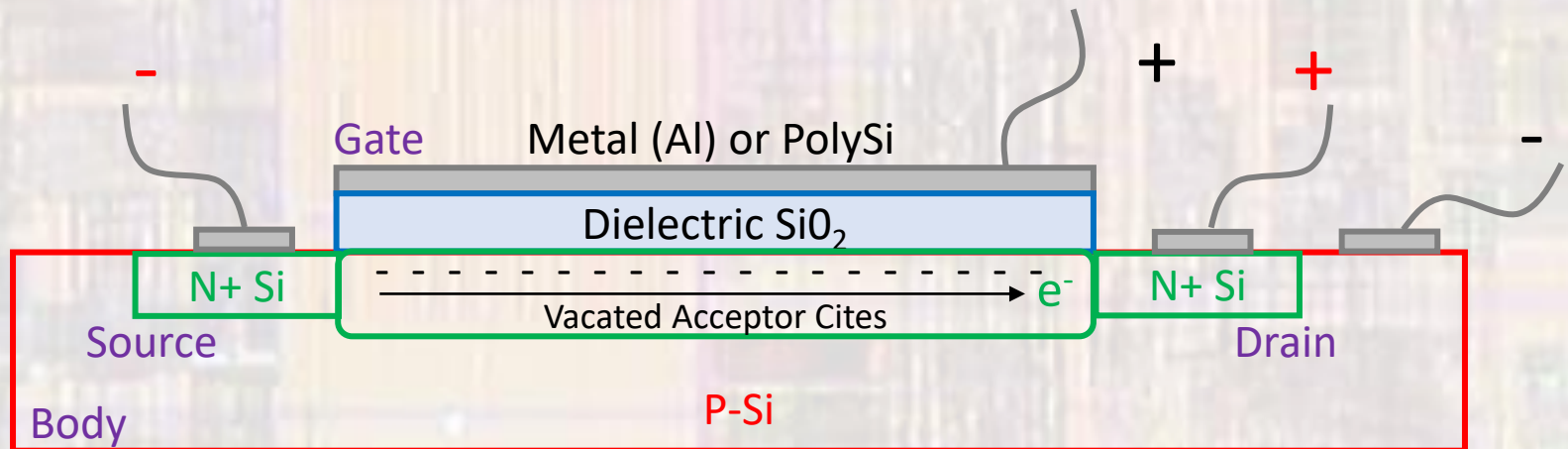


A channel is formed from Source to Drain
Electrons can flow through this channel

MOS Enhancement Mode Transistor

- N-MOS Operation

- **Large** Positive Bias + Positive Bias from Drain to Source
 - Electrons move from Source to Drain
 - Current flows from Drain to Source



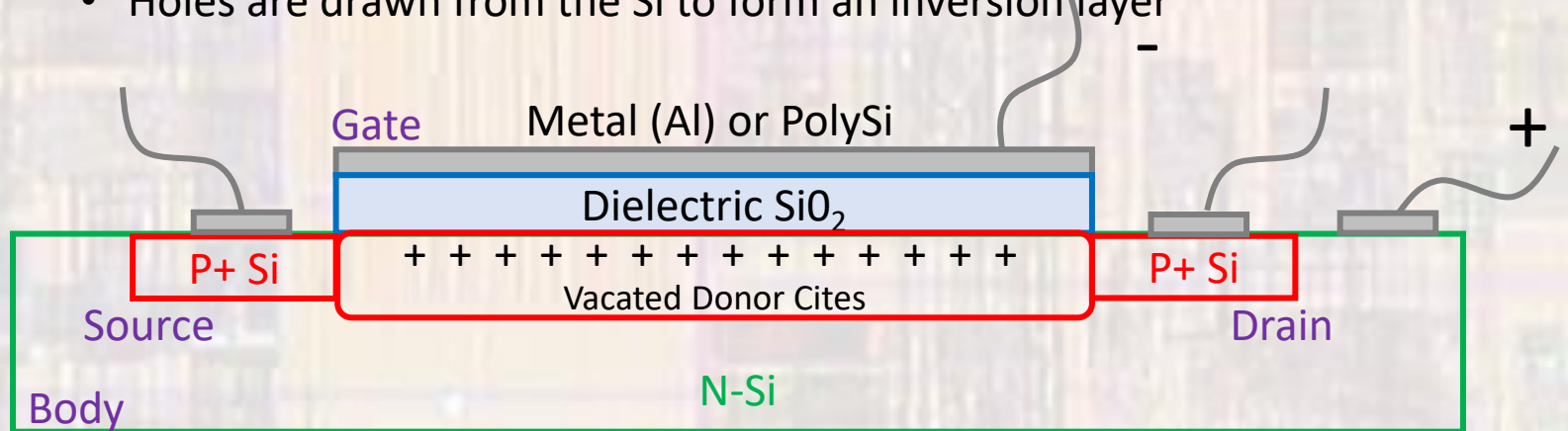
MOS Enhancement Mode Transistor

- P-MOS Operation

- **Large** Negative Bias

- Depletion region is formed

- Mobile electrons pushed away (region is depleted of electrons)
 - Net positive (fixed) charge left behind
 - Holes are drawn from the Si to form an inversion layer

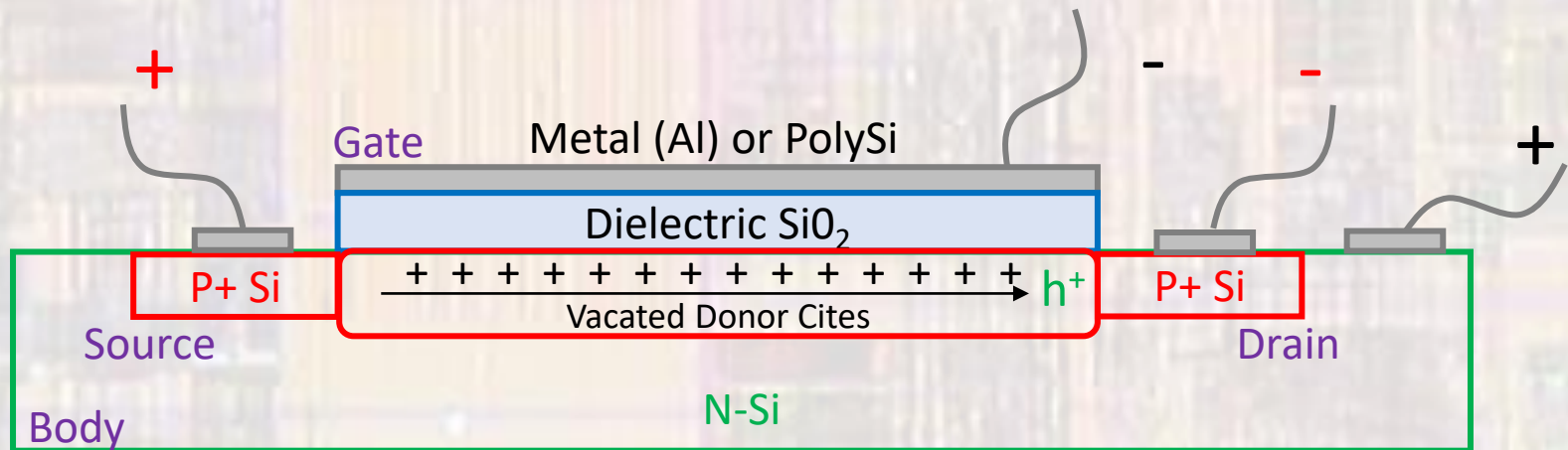


A channel is formed from Source to Drain
Holes can flow through this channel

MOS Enhancement Mode Transistor

- P-MOS Operation

- **Large** Negative Bias + Positive Bias from Source to Drain
 - Holes move from Source to Drain
 - Current flows from Source to Drain



MOS Enhancement Mode Transistor

- Parameters
 - W – width of the transistor
 - L – length of the transistor (S to D)
 - V_{th} – threshold voltage (inversion layer formed)
 - K_n, K_p – conduction parameter

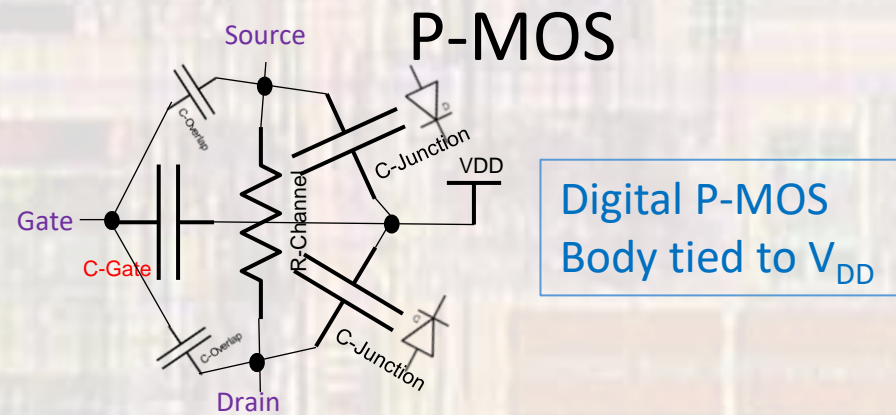
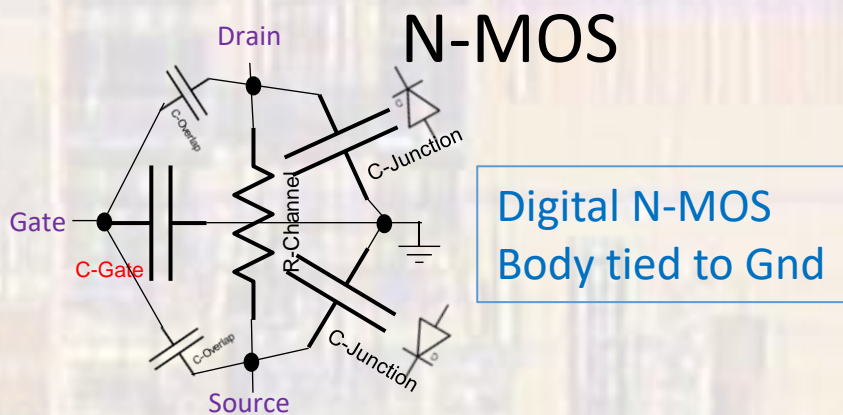
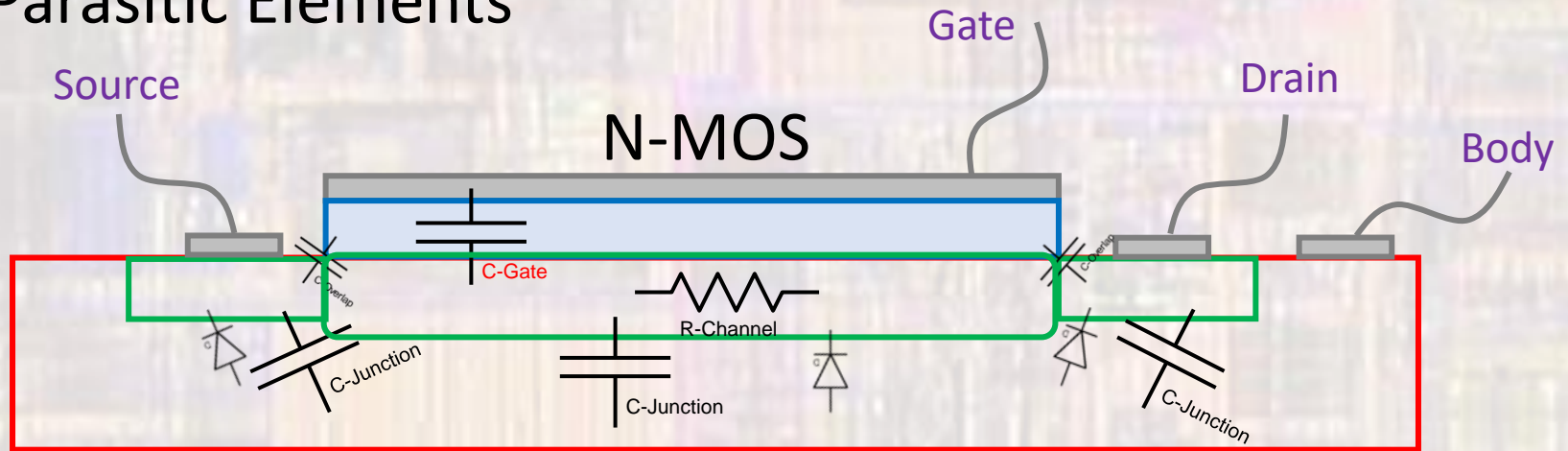
$$K_n = \frac{W \mu_n C_{ox}}{2L} \qquad K_p = \frac{W \mu_p C_{ox}}{2L}$$

$$K_n = \frac{k'_n W}{2 L} \qquad K_p = \frac{k'_p W}{2 L}$$
$$k'_n = \mu_n C_{ox} \qquad k'_p = \mu_p C_{ox}$$

μ_n, μ_p, C_{ox} fixed for a given semiconductor process

MOS Enhancement Mode Transistor

- Parasitic Elements



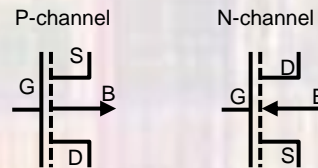
MOS Enhancement Mode Transistor

- Parasitic Elements
 - Gate
 - Capacitive
 - No DC current
 - AC/Transient current
 - S/D
 - Channel – Resistive
 - Dependent on V_{GS} and V_{DS}
 - Capacitive to Gnd (V_{DD})
 - No DC current
 - AC/Transient current
 - Reverse Biased Diode to Gnd (V_{DD})
 - Small leakage current independent of transistor action

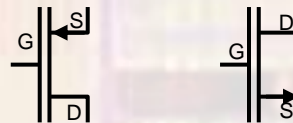
MOS Enhancement Mode Transistor

- Enhancement Mode
 - A bias is required to form the channel

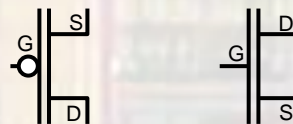
- 4-terminal symbol



- In digital applications the Source is typically tied to
 - Vdd for P-MOS
 - Gnd for N-MOS



- The simplified logic symbols

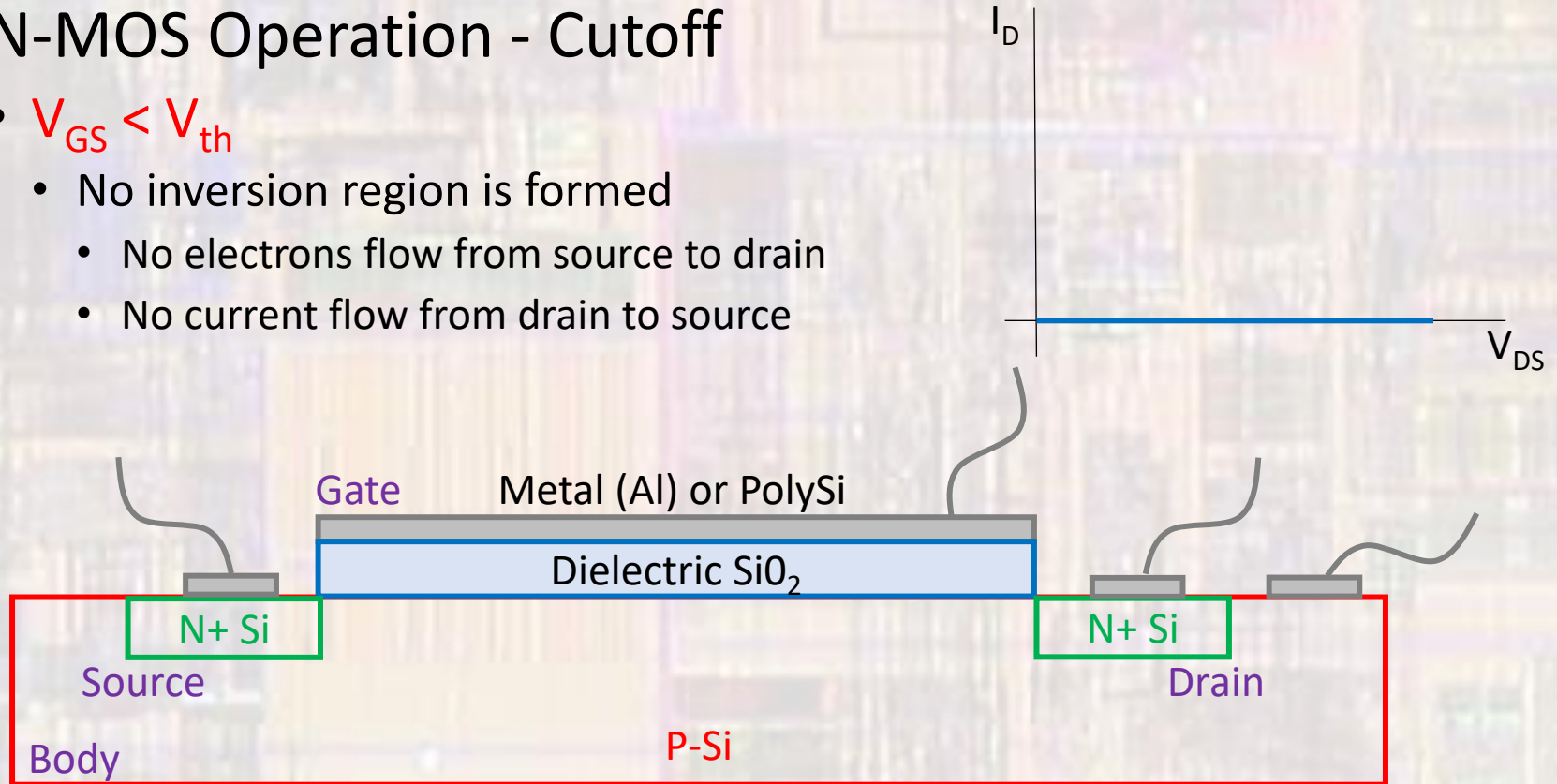


Note – almost all N-MOS and P-MOS devices used today are enhancement mode – so the dashed line is omitted

MOS I-V Characteristics

- N-MOS Operation - Cutoff

- $V_{GS} < V_{th}$
 - No inversion region is formed
 - No electrons flow from source to drain
 - No current flow from drain to source

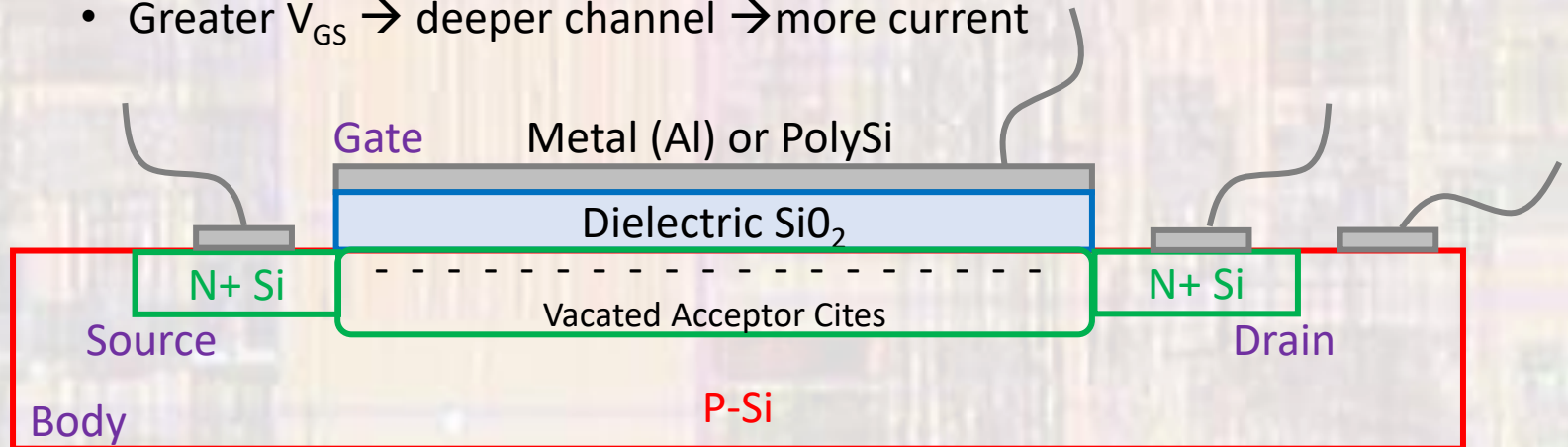
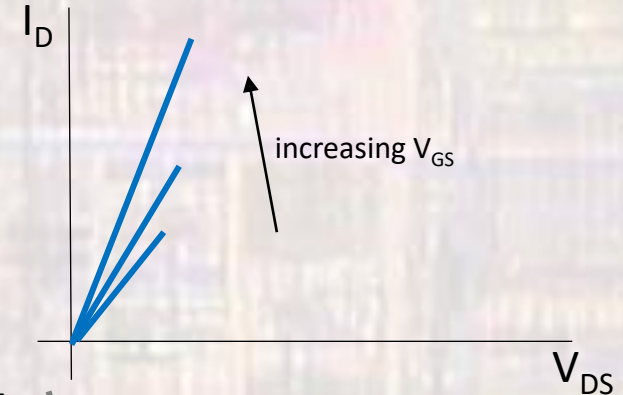


$$I_D = 0$$

MOS I-V Characteristics

- N-MOS Operation – Linear

- $V_{GS} > V_{th}$, $V_{DS} < V_{DSsat}$
 - Inversion region is formed
 - Electrons can flow from source to drain
 - Current can flow from drain to source
 - Greater $V_{GS} \rightarrow$ deeper channel \rightarrow more current



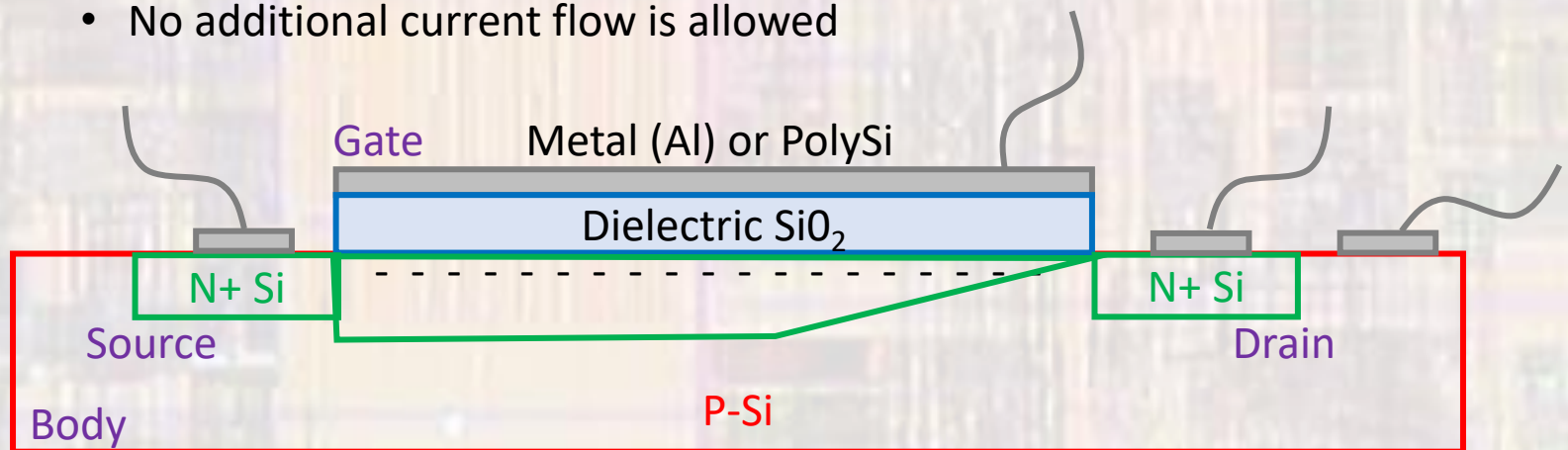
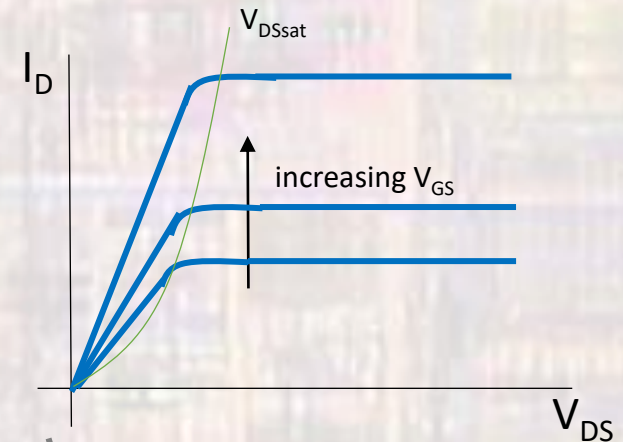
$$V_{DSsat} = V_{GS} - V_{th}$$

$$I_D = K_n [2(V_{GS} - V_{tn})V_{DS} - V_{DS}^2]$$

MOS I-V Characteristics

- N-MOS Operation – Saturation

- $V_{GS} > V_{th}$, $V_{DS} > V_{DSsat}$
 - Inversion region is formed
 - V_D is high enough to counteract the V_G near the drain \rightarrow “pinch-off” of the channel
 - No additional current flow is allowed



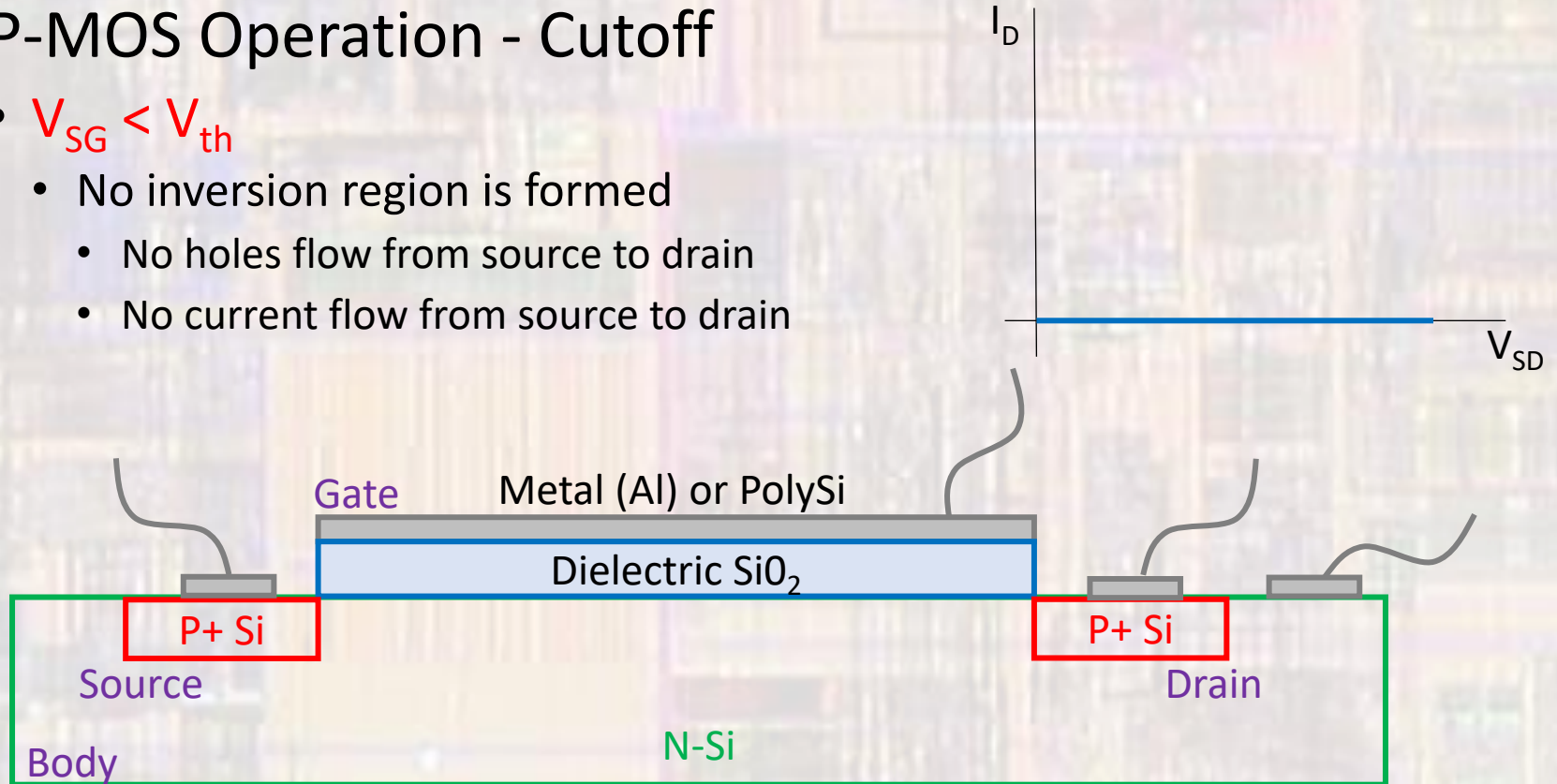
$$V_{DSsat} = V_{GS} - V_{th}$$

$$I_D = K_n (V_{GS} - V_{tn})^2$$

MOS I-V Characteristics

- P-MOS Operation - Cutoff

- $V_{SG} < V_{th}$
 - No inversion region is formed
 - No holes flow from source to drain
 - No current flow from source to drain

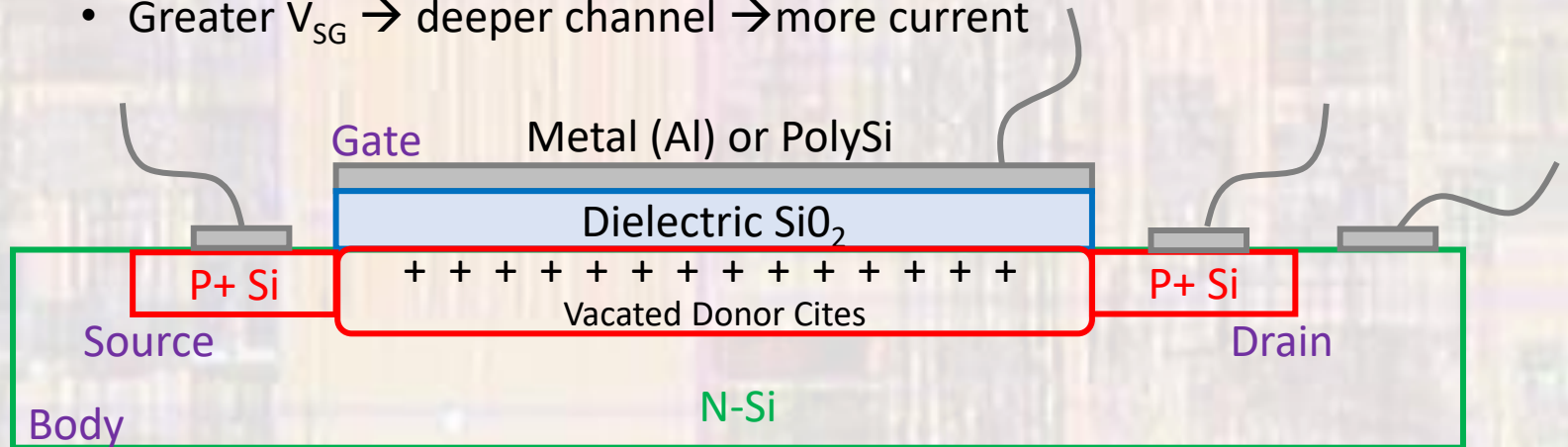
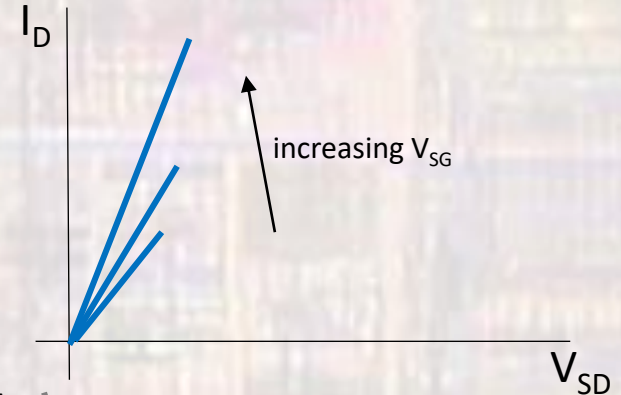


$$I_D = 0$$

MOS I-V Characteristics

- P-MOS Operation – Linear

- $V_{SG} > V_{th}$, $V_{SD} < V_{SDsat}$
 - Inversion region is formed
 - Holes can flow from source to drain
 - Current can flow from source to drain
 - Greater $V_{SG} \rightarrow$ deeper channel \rightarrow more current



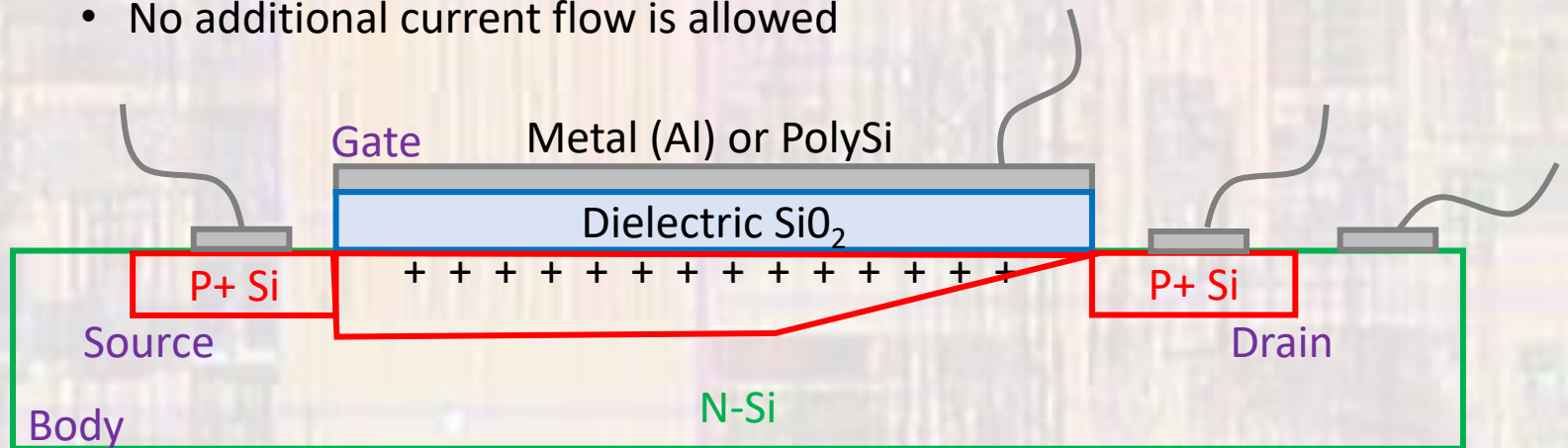
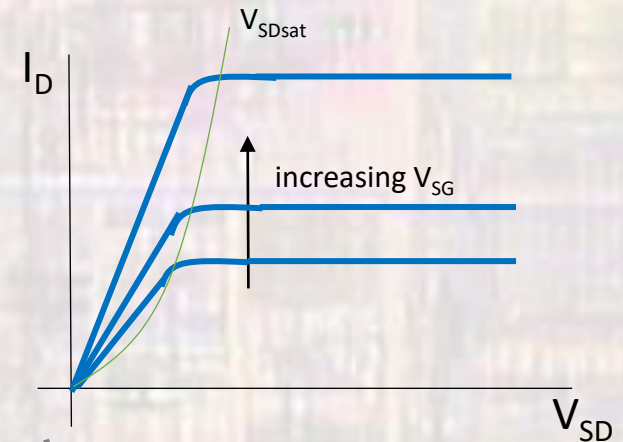
$$V_{SDsat} = V_{SG} - V_{th}$$

$$I_D = K_p [2(V_{SG} - V_{tp})V_{SD} - V_{SD}^2]$$

MOS I-V Characteristics

- P-MOS Operation – Saturation

- $V_{SG} > V_{th}$, $V_{SD} > V_{SDsat}$
 - Inversion region is formed
 - V_D is low enough to counteract the V_G near the drain \rightarrow “pinch-off” of the channel
 - No additional current flow is allowed



$$V_{SDsat} = V_{SG} - V_{th} \quad I_D = K_p (V_{SG} - V_{tp})^2$$

MOS I-V Characteristics

• Parameters

$$K_n = \frac{W \mu_n C_{ox}}{2L} \qquad K_p = \frac{W \mu_p C_{ox}}{2L}$$

$$K_n = \frac{k'_n W}{2 L} \qquad K_p = \frac{k'_p W}{2 L}$$

$$k'_n = \mu_n C_{ox} \qquad k'_p = \mu_p C_{ox}$$

μ_n, μ_p, C_{ox} fixed for a given semiconductor process \rightarrow

k'_n, k'_p fixed for a given semiconductor process

$$I_D = K_n [2(V_{GS} - V_{tn})V_{DS} - V_{DS}^2]$$

$$I_D = K_p [2(V_{SG} - V_{tp})V_{SD} - V_{SD}^2]$$

Linear

$$I_D = \frac{k'_n W}{2 L} [2(V_{GS} - V_{tn})V_{DS} - V_{DS}^2]$$

$$I_D = \frac{k'_p W}{2 L} [2(V_{SG} - V_{tp})V_{SD} - V_{SD}^2]$$

$$V_{DS} > V_{DSsat} \qquad V_{DSsat} = V_{GS} - V_{th}$$

$$V_{SDsat} = V_{SG} - V_{th} \qquad V_{SD} > V_{SDsat}$$

$$I_D = K_n (V_{GS} - V_{tn})^2$$

$$I_D = K_p (V_{SG} - V_{tp})^2$$

Saturation

$$I_D = \frac{k'_n W}{2 L} (V_{GS} - V_{tn})^2$$

$$I_D = \frac{k'_p W}{2 L} (V_{SG} - V_{tp})^2$$

MOS Gate Capacitance

- Parameters

- W – Transistor Width
- L – Transistor length (channel length)
- t_{ox} – thickness of the oxide
 - 15-20 Angstroms – 3 to 4 atom layers
 - $1.5 - 2.0 \times 10^{-9}$ m
- ϵ_0 – permittivity (dielectric constant) of free space
 - 8.85×10^{-12} F/m
- $\epsilon_r(\text{SiO}_2)$ – relative permittivity multiplier for SiO_2
 - 3.9

$$C_G = W \times L \times C_{ox} = W \times L \times \epsilon_{ox} / t_{ox} = W \times L \times \epsilon_0 \epsilon_r / t_{ox}$$

$$C_{Gn} = W \times L \times k'_n / \mu_n$$

$$C_{Gp} = W \times L \times k'_p / \mu_p$$